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ABSTRACT OF THE DISCLOSURE

A semiconductor device is provided in the form of a chip carrier (e.g., chip/IC scale carrier for RF applications) that includes an integrated circuit chip attached to a die attach pad. The device has an interconnect substrate having an upper surface and a lower surface, with a plurality of vias passing through the thickness of the interconnect substrate from the upper surface to the lower surface. The die attach pad is located on the upper surface of the interconnect substrate, and a heat spreader is located on the lower surface of the interconnect substrate. A first group of vias is positioned to intersect both the die attach pad and the heat spreader. A second group of vias is positioned away from the die attach pad and the heat spreader. The upper surface has a plurality of bond pads that are abutting the second group of vias and the lower surface has a plurality of lands that are also abutting the second group of vias.